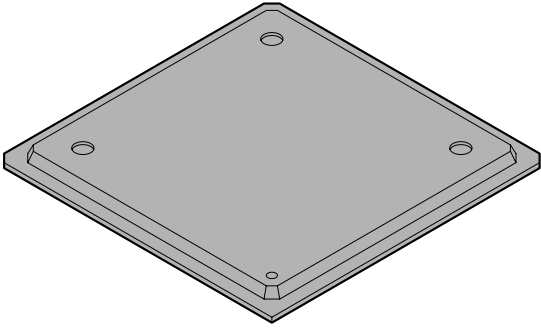
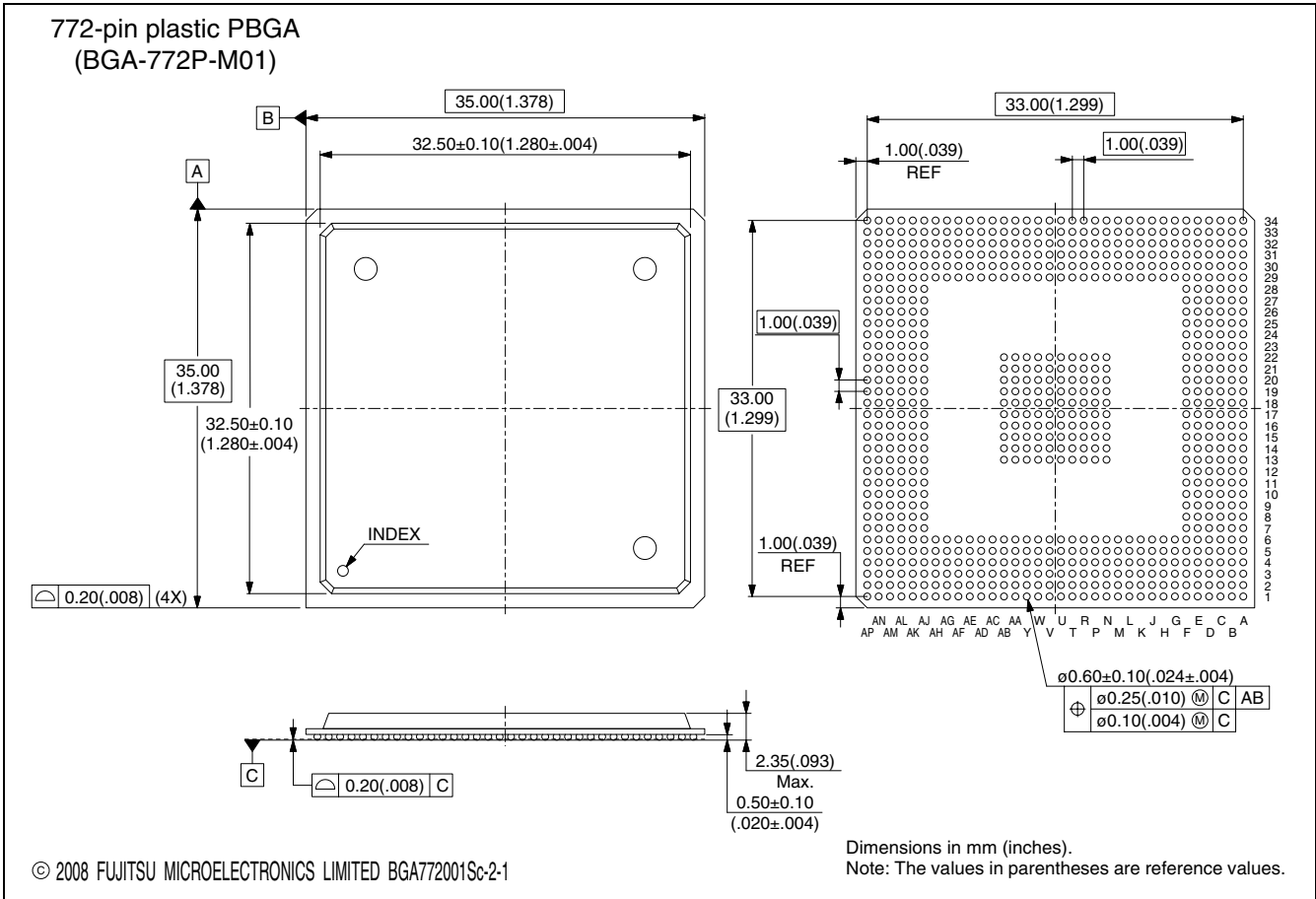


BGA-772P-M01

<p>772-pin plastic PBGA</p>  <p>(BGA-772P-M01)</p>	Lead pitch	1.00 mm
	Package width × package length	35.00 mm × 35.00 mm
	Lead shape	Ball
	Sealing method	Plastic mold
	Mounting height	2.35 mm MAX
	Weight	4.80 g



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